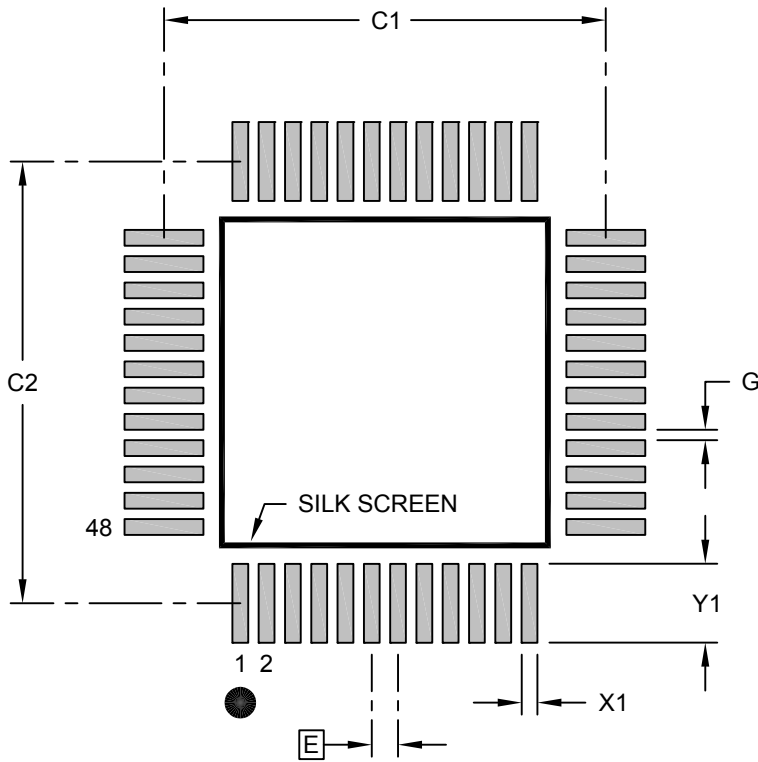


48-Lead Plastic Thin Quad Flatpack (Y8X) - 7x7x1.0 mm Body [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

| | Units | MILLIMETERS | | |
|--------------------------|------------------|-------------|------|------|
| | | MIN | NOM | MAX |
| | Dimension Limits | | | |
| Contact Pitch | E | 0.50 BSC | | |
| Contact Pad Spacing | C1 | | 8.40 | |
| Contact Pad Spacing | C2 | | 8.40 | |
| Contact Pad Width (X48) | X1 | | | 0.30 |
| Contact Pad Length (X48) | Y1 | | | 1.50 |
| Distance Between Pads | G | 0.20 | | |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process